

US00D760178S

(12) **United States Design Patent**
Feng

(10) **Patent No.:** **US D760,178 S**
(45) **Date of Patent:** **** Jun. 28, 2016**

- (54) **LIGHT EMITTING DIODE CHIP**
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Taoyuan (TW)
- (**) Term: **14 Years**
- (21) Appl. No.: **29/489,410**
- (22) Filed: **Apr. 30, 2014**
- (30) **Foreign Application Priority Data**

Jan. 28, 2014 (TW) 103300561

- (51) **LOC (10) Cl.** **13-03**
- (52) **U.S. Cl.**

USPC **D13/180**

- (58) **Field of Classification Search**

USPC D13/180; D26/1; D25/152, 155, 160,
D25/163

CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;
H01L 27/156; H01L 31/02; H01L 33/00;
H01L 33/0079; H01L 33/04; H01L 33/08;
H01L 33/10; H01L 33/20; H01L 33/38;
H01L 33/42; H01L 33/483; H01L 33/486;
H01L 24/06; F21K 9/00; F21K 9/30; F21K
9/54; H01J 3/021; H01S 5/34; B82Y 20/00;
B82Y 40/00

See application file for complete search history.

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(57) **CLAIM**

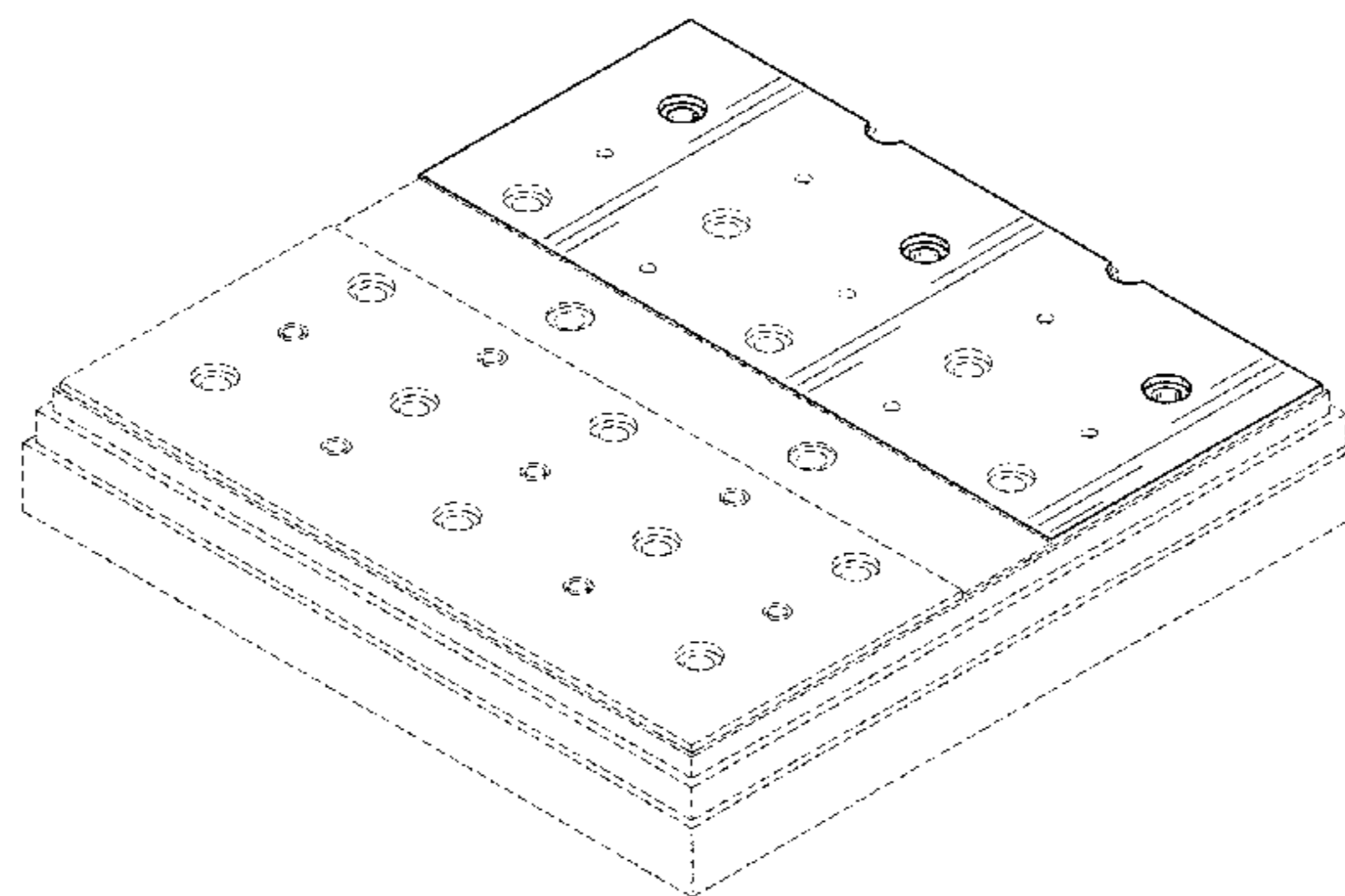
The ornamental design for a light emitting diode chip, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a light emitting diode chip showing of my new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a left side view thereof;
FIG. 5 is a right side view thereof;
FIG. 6 is a top view thereof; and,
FIG. 7 is a bottom view thereof.

The broken line portions of the light emitting diode chip in FIGS. 1-7 represent unclaimed portions of the design and form no part thereof.

1 Claim, 5 Drawing Sheets



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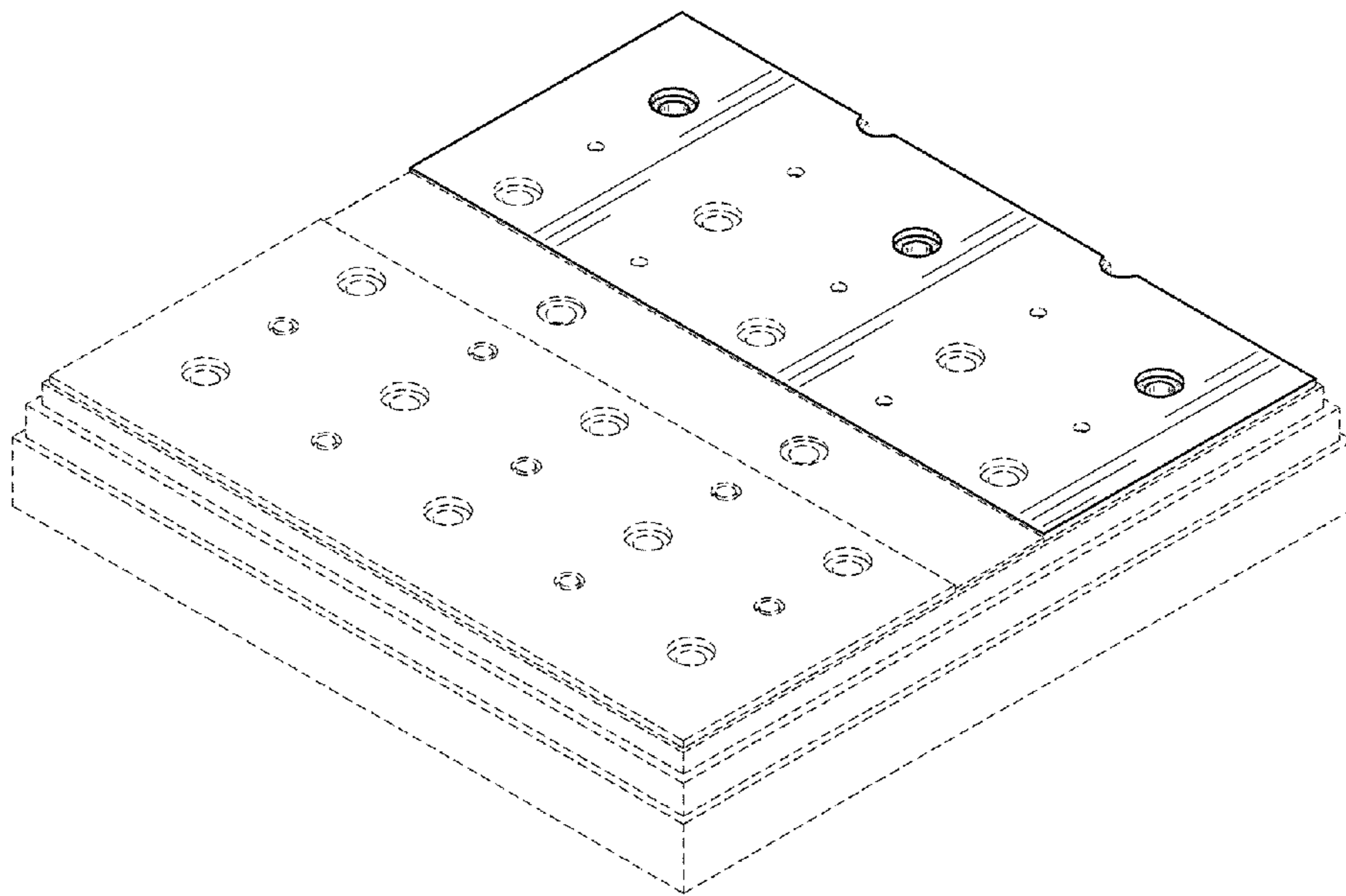


FIG. 1

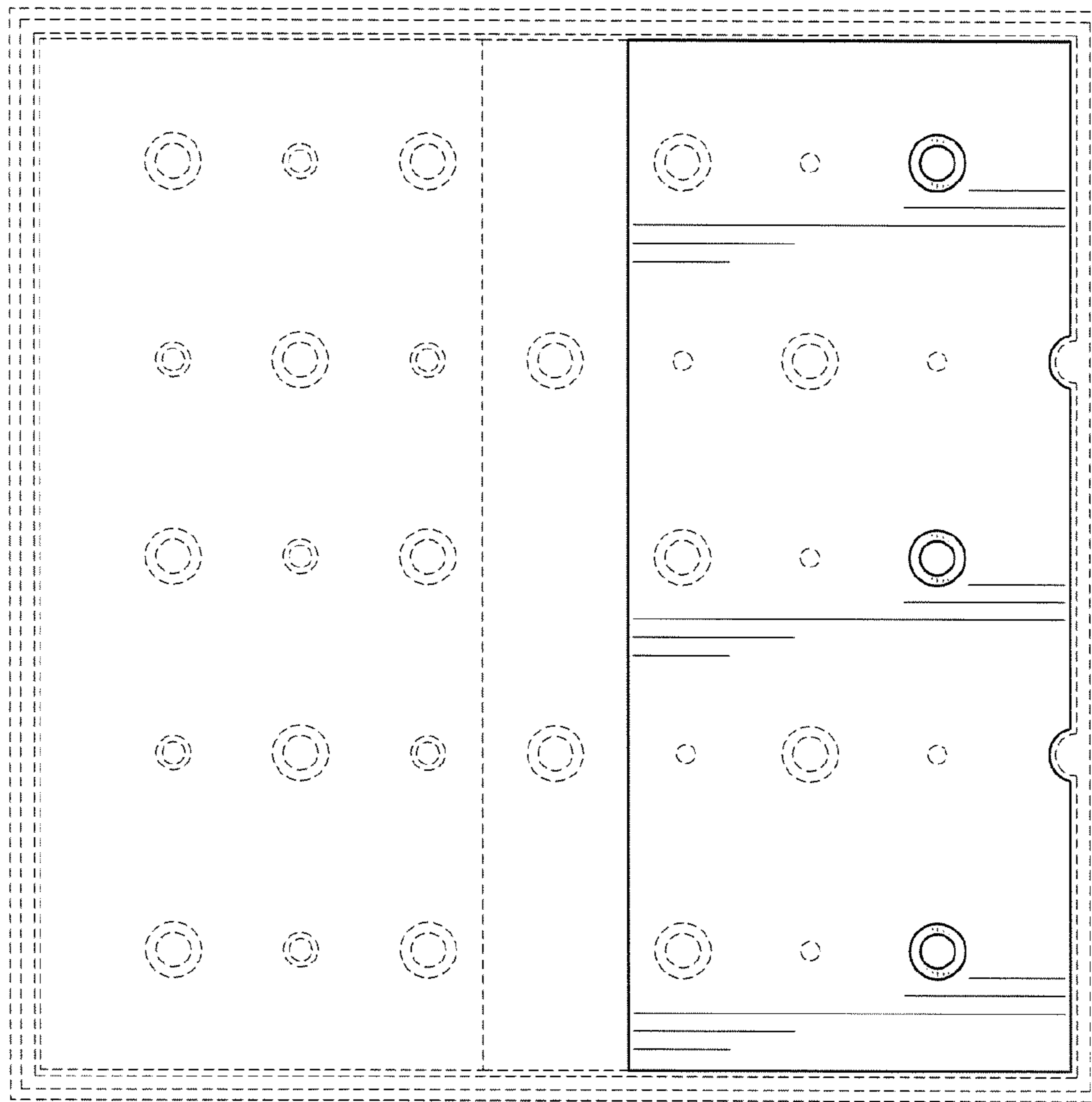


FIG. 2

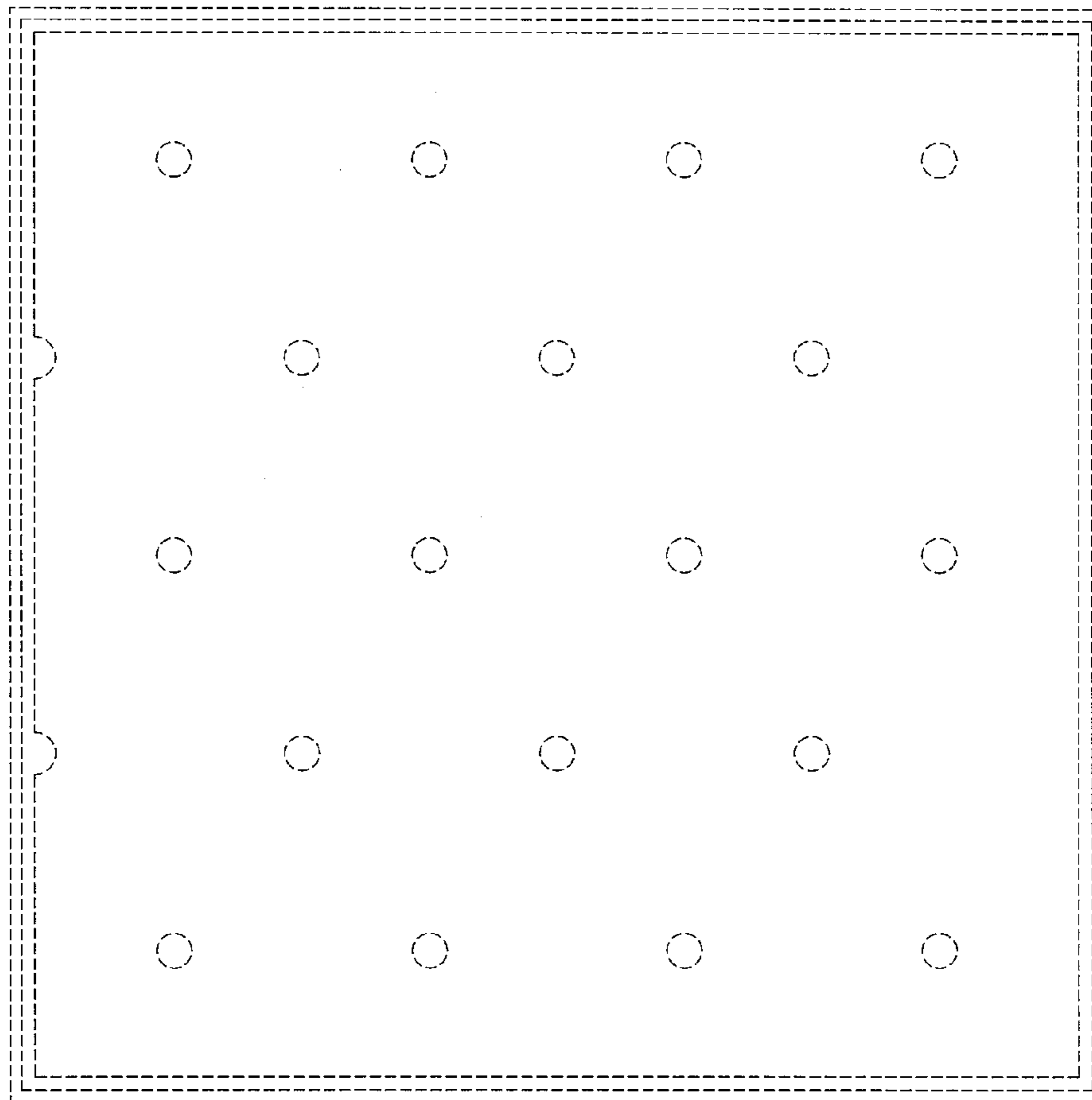


FIG. 3

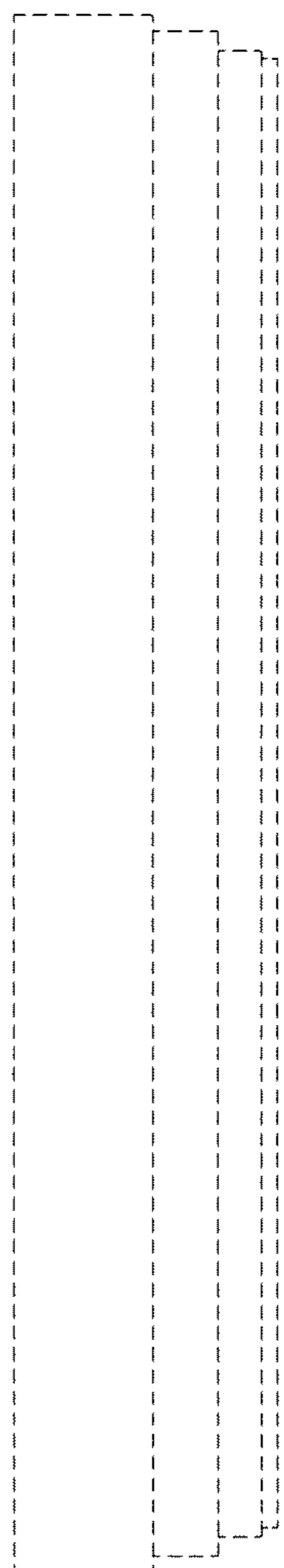


FIG. 4

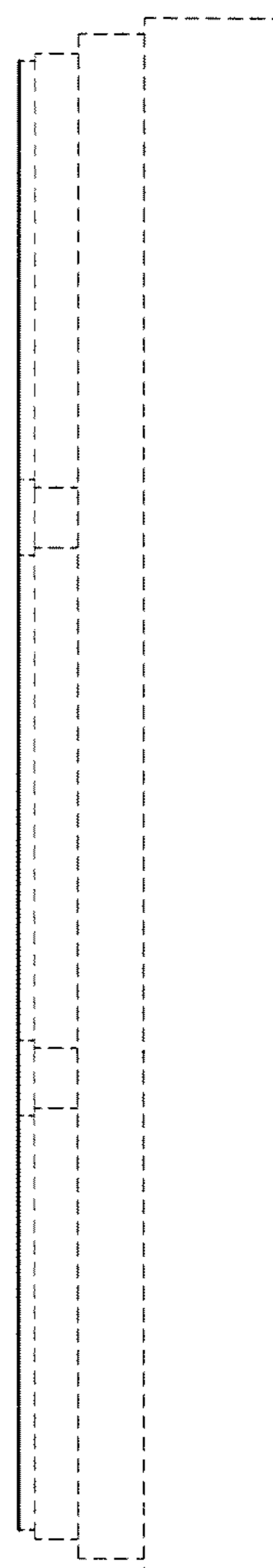


FIG. 5

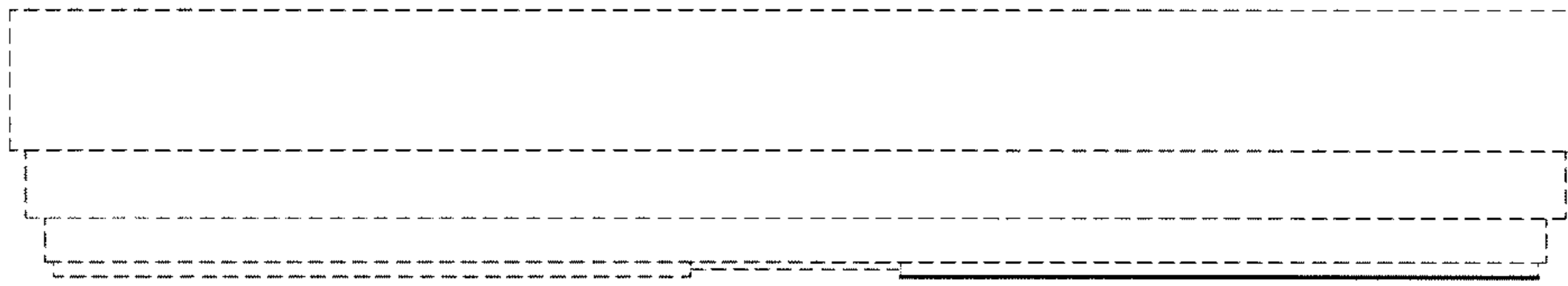


FIG. 6

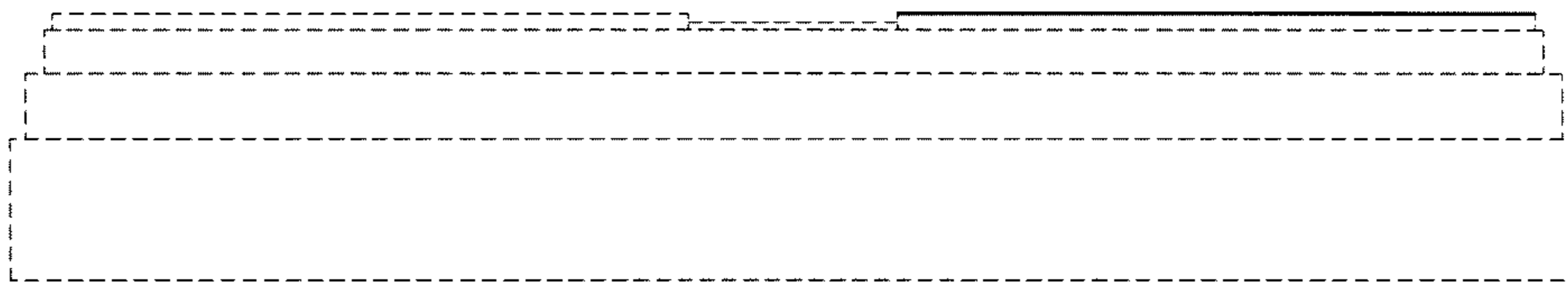


FIG. 7